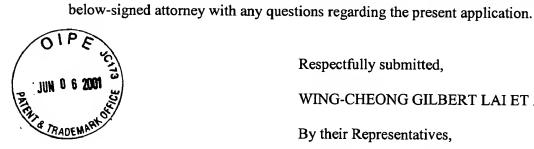
Serial Number: 09/782,498 Filing Date: February 13, 2001

SMALL GRAIN SIZE, CONFORMAL ALUMINUM INTERCONNECTS AND METHOD FOR THEIR FORMATION

Claims 17-52 are now pending in this application. The Examiner is invited to contact the



Respectfully submitted,

WING-CHEONG GILBERT LAI ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. P.O. Box 2938 Minneapolis, MN 55402

(612) 373-6976

Reg. No. 37,650

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this \_\_\_\_\_ day of June, 2001.

Name

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